

IN THE SPECIFICATION:

Please replace paragraph number [0007] with the following rewritten paragraph:

[0007] Larger circuit boards, such as so-called “motherboards” and the substrates of ~~so-called~~ “plug-and-play” devices or cards, may be configured to carry a plurality of semiconductor devices. As with interposers, the trend with such larger circuit boards is also toward ~~ever-ever-decreasing~~ sizes and ever-increasing densities. Consequently, contamination of the connection surfaces of terminals by adhesive material is increasingly encountered when semiconductor devices are assembled with larger circuit boards.

Please replace paragraph number [0052] with the following rewritten paragraph:

[0052] A variety of known, suitable processes may be employed to form solder mask 30 either separately from or on a circuit board. By way of example only, known photolithography techniques, which include the use of a liquid photoresist material, a pattern on a reticle to be copied to a layer of the photoresist material, radiation of a suitable wavelength for exposing selected regions of the layer of photoresist material through the reticle, and ~~resist-resist~~-developing chemicals that are appropriate for use with the photoresist material. Dry film photoresist materials are also known and suitable for use in the present invention may be employed. As another example, stereolithographic techniques may be used to form solder mask 30 from one or more layers of a photocurable polymer by selectively exposing regions of each layer of photocurable polymer, one layer at a time, to cure the selectively exposed regions.